



## PR/096025 | Senior Manager, Bumping

### Job Information

**Recruiter**

JAC Recruitment Singapore

**Job ID**

1560741

**Industry**

Electronics, Semiconductor

**Job Type**

Permanent Full-time

**Location**

Singapore

**Salary**

Negotiable, based on experience

**Refreshed**

October 7th, 2025 10:24

### General Requirements

**Career Level**

Mid Career

**Minimum English Level**

None

**Minimum Japanese Level**

None

**Minimum Education Level**

Associate Degree/Diploma

**Visa Status**

No permission to work in Japan required

### Job Description

#### Company and Job Overview

This is an semiconductor manufacturing company, they are looking for a Senior Manager to oversee the Process Engineering of Wafer Bumping

#### The role

Responsible for overseeing and optimizing manufacturing processes, leading process improvements, and managing a team of process engineers to ensure efficiency, cost-effectiveness, and quality. Support new product development and ramp-up activities within company guidelines and industry best practices, while driving continuous growth, quality, and process enhancements.

#### Responsibilities

Lead and mentor engineers within the Bump Process Department to enhance technical capabilities and foster continuous professional growth.

Serve as the technical project leader, managing cross-functional teams to ensure new product development aligns with the company roadmap.

Oversee projects from inception to pre-production, ensuring adherence to schedules, budgets, and company system requirements.

Drive smooth project execution while addressing technical challenges and ensuring customer requirements are met.

Collaborate with other departments such as R&D, Production, Quality, and Supply Chain to ensure seamless integration of new processes and technologies into the manufacturing workflow.

Provide technical expertise and guidance during the development and scaling of new products and processes.

Contribute actively in promoting company technological capability through customers' presentation.

Actively contribute to proposal development and technical discussions during business negotiations.

#### Qualifications

Bachelor's degree in Engineering or a related field

At least 10 years experience with semiconductor bumping processes and lean Six Sigma methodology.

Minimum of 5 years of leadership experience in a technical or engineering environment

#### Additional Notes:

This is a confidential search for a replacement role. Only shortlisted candidates will be shared with the company before the first-round interview.

Catherine Qu  
JAC Recruitment Pte Ltd  
EA Personnel: R22104823  
EA Personnel Name: QU QIUSHI

#LI-JACSG  
#countrysingapore

**Notice:** By submitting an application for this position, you acknowledge and consent to the disclosure of your personal information to the Privacy Policy and Terms and Conditions, for the purpose of recruitment and candidate evaluation.

Privacy Policy Link: <https://www.jac-recruitment.sg/privacy-policy>  
Terms and Conditions Link: <https://www.jac-recruitment.sg/terms-of-use>

---

#### Company Description